RICOH

R3118x SERIES

LOW VOLTAGE DETECTOR with individual SENSE pin and delay function

NO.EA-242-160229

OUTLINE

The R3118x series are CMOS-based voltage detector ICs with individual sense pin, high detector threshold accuracy and delay time, and ultra-low supply current, which can be operated at an extremely low voltage and is used for system reset as an example.

Each of these ICs consists of a voltage reference unit, a hysteresis comparator, resistors net for detector threshold setting, an output driver transistor, and a delay circuit.

V_{DD} supply pin for the IC and voltage supervisory sense pin are individual, therefore the output pin can keep "L" level even if the sense pin voltage is going down to 0V, or there is no indefinite range for the sense pin.

Since a delay circuit is built-in, by connecting an external capacitor, any output delay time can be set. In the R3118x series, detector released delay time can be set, and detector delay time is not influenced by the external capacitor for the delay time.

The detector threshold is fixed with high accuracy internally and does not require any adjustment.

The tolerance of the detector threshold is ±22.5mV (-V_{DET_S}<1.6V) or ±1.5% (-V_{DET_S}≥1.6V).

Minimum detector threshold voltage is 0.6V, ultra low voltage detector threshold can be set.

Output delay time for the detector release can be set with high accuracy. The tolerance of the IC side is $\pm 30\%$.

Two output types, Nch open drain type and CMOS type are available. If the sense pin voltage becomes to equal or lower than the detector threshold voltage, the output voltage becomes "L", and if the sense pin voltage becomes to released voltage, the output voltage becomes "H" after the set delay time.

Three types of packages, SOT-23-5, SC-88A, and DFN(PLP)1212-6 are available.

FEATURES*

Supply Current	Typ. 0.4μA (Vsense≥+Vdet, Vdd=6V)
	Consumption current through SENSE pin is not included.
Operating Voltage Range	1.0V to 6.0V (-40°C≤Topt≤85°C)
Detector Threshold Range	0.6V to 5.0V (0.1V steps)
	(For other voltages, please refer to MARK INFORMATIONS.)
Accuracy Detector Threshold	±1.5% (-V _{DET_} s≥1.6V), ±22.5mV (-V _{DET_} s<1.6V)
Temperature-Drift Coefficient of Detector Threshol	dTyp. ±30ppm/°C
Accuracy Detector Released	±30%
Temperature-Drift Coefficient of Detector Released	∃Typ. ±0.16ppm/°C
Output Types	Nch Open Drain and CMOS
Packages	DFN(PLP)1212-6, SC-88A , SOT-23-5
	* Topt=25°C, unless otherwise noted.

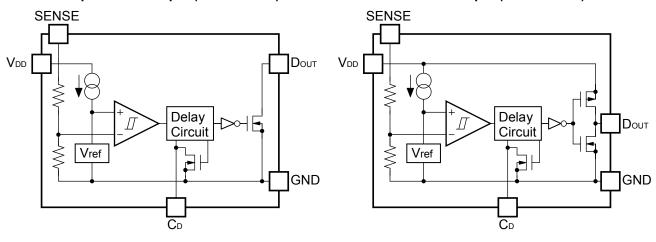
APPLICATIONS

- · CPU and Logic Circuit Reset
- · Battery Checker
- Window Comparator / Level discrimination
- · Battery Back-up Circuit
- Power Failure Detector

BLOCK DIAGRAMS

Nch Open Drain Output (R3118xxxxA)

CMOS Output (R3118xxxxC)



SELECTION GUIDE

The package type, the detector threshold, the output type and the taping type for the ICs can be selected at the users' request.

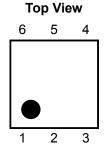
Product Name Package		Quantity per Reel	Pb Free	Halogen Free
R3118Kxx1*-TR	DFN(PLP)1212-6	5,000 pcs	Yes	Yes
R3118Qxx2*-TR-FE	SC-88A	3,000 pcs	Yes	Yes
R3118Nxx1*-TR-FE	SOT-23-5	3,000 pcs	Yes	Yes

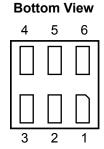
xx: The detector threshold can be designated in the range from 0.6V(06) to 5.0V(50) in 0.1V steps. (For other voltages, please refer to MARK INFORMATIONS.)

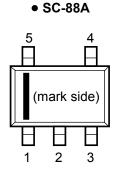
- * : Designation of Output Type
 - (A) Nch Open Drain
 - (C) CMOS

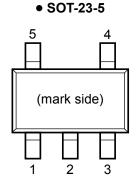
PIN CONFIGURATIONS

• DFN(PLP)1212-6









PIN DESCRIPTIONS

• DFN(PLP)1212-6

Pin No.	Symbol	Description
1	SENSE	Voltage Detector Voltage Sense Pin
2	GND	Ground Pin
3	С	Pin for External Capacitor (for setting output delay)
4	V _{DD}	Input Pin
5	NC	No Connection
6	D оит	Output Pin ("L" at detection)

• SC-88A

	Pin No.	Symbol	Description
	1	D оит	Output Pin ("L" at detection)
2		GND	Ground Pin
	3	V_{DD}	Input Pin
	4 C _D		Pin for External Capacitor (for setting output delay)
	5	SENSE	Voltage Detector Voltage Sense Pin

• SOT-23-5

Pin No.	Symbol	Description
1	D оит	Output Pin ("L" at detection)
2	V_{DD}	Input Pin
3	GND	Ground Pin
4	С	Pin for External Capacitor (for setting output delay)
5	SENSE	Voltage Detector Voltage Sense Pin

ABSOLUTE MAXIMUM RATINGS

Symbol	Item	Rating	Unit
V_{DD}	Supply Voltage	-0.3 to 7.0	V
Vsense	SENSE Pin Voltage	-0.3 to 7.0	V
VDOUT	Output Voltage (Nch Open Drain Output)	-0.3 to 7.0	V
V DOUT	Output Voltage (CMOS Output)	-0.3 to V _{DD} +0.3	V
la a un	Output Current Nch Driver (Sink Current)	20	mA
Іроит	Output Current Pch Driver (Source Current)	-5	IIIA
	Power Dissipation (DFN(PLP)1212-6) *	400	
P_D	Power Dissipation (SC-88A)*	380	mW
	Power Dissipation (SOT-23-5) *	420	
Topt	Operating Temperature Range	-40 to 85	°C
Tstg	Storage Temperature Range	-55 to 125	°C

^{*)} For Power Dissipation, please refer to PACKAGE INFORMATION.

ABSOLUTE MAXIMUM RATINGS

Electronic and mechanical stress momentarily exceeded absolute maximum ratings may cause the permanent damages and may degrade the life time and safety for both device and system using the device in the field. The functional operation at or over these absolute maximum ratings is not assured.

ELECTRICAL CHARACTERISTICS

• R3118xxxxA/C

values indicate −40°C≤Topt≤85°C, -V_{DET_S} means set detector threshold, V_{DD}=1V to 6V, unless otherwise noted.

Topt=25°C

Symbol	Item	Conditions		Min.	Тур.	Max.	Unit
V _{DD}	Operating Voltage			1		6	V
		-V _{DET_S} <1.6V	Topt=25°C	-V _{DET_S} -0.0225	-V _{DET_} s	-V _{DET_S} +0.0225	
-VDET	Detector Threshold		–40°C≤Topt≤85°C	-V _{DET_S} -0.0375	-VDET_S	-V _{DET_} s +0.0375	V
- V DE1	-VDET Detector infestion	Topt=25°C -VDET_S≥1.6V -40°C≤Topt≤85°C	Topt=25°C	-V _{DET_S} × 0.985	-V _{DET_} s	-V _{DET_} s × 1.015	
			-V _{DET_S} × 0.975	-V _{DET_} s	-V _{DET_} s × 1.025		
V _{HYS}	Detector threshold	Topt=25°C		-V _{DET_} s × 0.040	$\begin{array}{c} -V_{\text{DET_S}} \\ \times \ 0.055 \end{array}$	-V _{DET_S} × 0.070	V
VHYS	Hysteresis	–40°C≤Topt≤8	5°C	-V _{DET_S} × 0.035	$\begin{array}{c} -V_{\text{DET_S}} \\ \times \ 0.055 \end{array}$	-V _{DET_s} × 0.075	V

Symbol	Item	Conditions		Min.	Тур.	Max.	Unit	
Iss	Supply Current *1	V _{SENSE} =0V, V _{DD} =6V			0.480	1.450		
155	Supply Current	VSENSE=6V, V	DD=6V		0.400	1.200	μΑ	
RSENSE	Sense Resistor	VSENSE=6V, V	DD=6V	9	34	58	$M\Omega$	
			V _{DD} =1V, V _{DOUT} =0.1V	0.150				
			V _{DD} =3V, V _{DOUT} =0.1V	0.550				
		Nch	VDD=5V, VDOUT=0.1V	0.850			mA	
	0 1 10 1	Vsense=0V	V _{DD} =1V, V _{DOUT} =0.4V	0.400			IIIA	
Іроит	Output Current (Driver Output Pin))	VDD=3V, VDOUT=0.4V	2.100				
			VDD=5V, VDOUT=0.4V	3.300				
			D - *2	VDD=1V, VDOUT=0.9V	6			
				Pch*2 V _{SENSE} =6V	VDD=3V, VDOUT=2.9V	30		
		V SENSE—O V	VDD=5V, VDOUT=4.9V	45				
I _{LEAK}	Nch Driver Leakage Current *3	VSENSE=6V, V	DD=6V, VDOUT=6V			80	nA	
	0 . 6	VSENSE=6V, V	DD=1V, VCD=0.4V	2.200		6.200		
Rois	C _D pin Discharge Tr. On Resistance	VSENSE=6V, VDD=3V, VCD=0.4V		0.400		1.250	kΩ	
	On resistance	Vsense=6V, Vdd=5V, Vcd=0.4V		0.250		0.800		
t reset	Detect Output Delay Time *4	Topt=25°C			80		μS	
+	Release Output	Topt=25°C		70	100	130		
t delay	Delay Time*5	–40°C≤Topt≤85°C		65	100	145	ms	

All of unit are tested and specified under load conditions such that $T_{opt}=25^{\circ}C$ except for Detector Threshold Temperature Coefficient, Detector Output Delay Time and Release Output Delay Time.

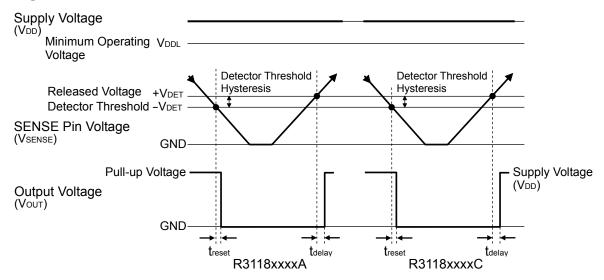
- *1: Consumption current through SENSE pin is not included.
- *2: In case of CMOS type
- *3: In case of Nch Open Drain type
- *4: In the case of CMOS output type: In the case that a 0.022μF capacitor is connected to the C_D pin, the time interval from forcing pulsive voltage between -V_{DET_S}×1.155V and -V_{DET_S}×0.9 to SENSE pin, to when the output voltage of the D_{OUT} pin will reach from "H" to V_{DD}/2.
 - In the case of Nch Open drain output type: In the case that a $0.022\mu\text{F}$ capacitor is connected to the C_D pin and the D_{OUT} pin is pulled up to 5V with 470k Ω , the time interval from forcing pulsive voltage between $V_{\text{DET_S}} \times 1.155 \text{V}$ and - $V_{\text{DET_S}} \times 0.9 \text{V}$ to SENSE pin, to when the output voltage reaches from "H" to 2.5V.
- *5: In the case of CMOS output type: In the case that a 0.022μF capacitor is connected to the C_D pin, the time interval from forcing pulsive voltage between -V_{DET_S}×0.9 and -V_{DET_S}×1.155V to SENSE pin, to when the output voltage of the D_{OUT} pin will reach from "L" to V_{DD}/2.
 - In the case of Nch Open drain output type: In the case that a $0.022\mu\text{F}$ capacitor is connected to the C_D pin and the D_{OUT} pin is pulled up to 5V with $470k\Omega$, the time interval from forcing pulsive voltage between $V_{\text{DET_SX}}$ 0.9V and - $V_{\text{DET_SX}}$ 1.155V to SENSE pin, to when the output voltage reaches from "L" to 2.5V.

RECOMMENDED OPERATING CONDITIONS (ELECTRICAL CHARACTERISTICS)

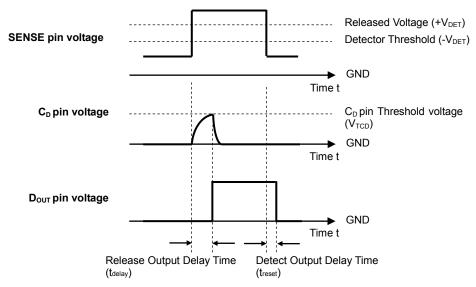
All of electronic equipment should be designed that the mounted semiconductor devices operate within the recommended operating conditions. The semiconductor devices cannot operate normally over the recommended operating conditions, even if when they are used over such conditions by momentary electronic noise or surge. And the semiconductor devices may receive serious damage when they continue to operate over the recommended operating conditions.



TIMING CHART



DESCRIPTION OF OUTPUT DELAY OPERATION



Output Delay Operation Diagram

DEFINITION OF OUTPUT DELAY TIME

A higher voltage than the released voltage is forced to the SENSE pin, charge to the capacitor connected to C_D pin is started, then the C_D pin voltage increases. Until C_D pin voltage reaches to C_D pin threshold voltage, the output of D_{OUT} pin voltage keeps "L", then when C_D pin voltage is higher than C_D pin threshold voltage, the D_{OUT} pin voltage changes from "L" to "H". The released output delay time means the time interval from when the released voltage threshold or more voltage level is forced to SENSE pin to when D_{OUT} voltage changes from "L" to "H".

When the voltage of Dout pin reverses from "L" to "H", the discharge of the external capacitor connected to CD pin starts. Therefore, the time interval from when the voltage lower than the detector threshold is forced to SENSE pin, to when the output voltage reverses from "H" to "L", or detector output delay time is constant and independent from the external capacitance value.

*1. After the Dout pin voltage reverses from "L" to "H", if a voltage lower than the detector threshold is forced to SENSE pin before the capacitor connected to C_D pin is discharged, delay time will increase. The time interval (t_{DIS}) from when the capacitor connected to C_D pin is discharged completely to when the capacitor is charged to a certain C_D pin voltage (described as V_{CD} herein) can be calculated by power supply voltage (V_{DD}), external capacitance (C_D), on resistance of the C_D pin discharge transistor (R_{DIS}) as in the next formula:

$$t_{DIS} = -R_{DIS} \times C_{D} \times In(V_{CD}/V_{DD} \times 0.45))$$

- *2. During the released delay operation, only a small current will charge the external capacitor connected to C_D pin. If the leakage current between C_D pin and GND is large, the released delay time may increase or the detector may not be released.
- *3. During the released delay operation, if the V_{DD} pin voltage varies, the released output delay time will be also shift.

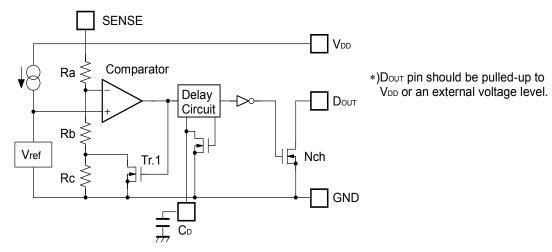
• How to calculate the released output delay time

The release output delay time (t_{delay}) can be calculated as in the next formula with an external capacitance value (C_D):

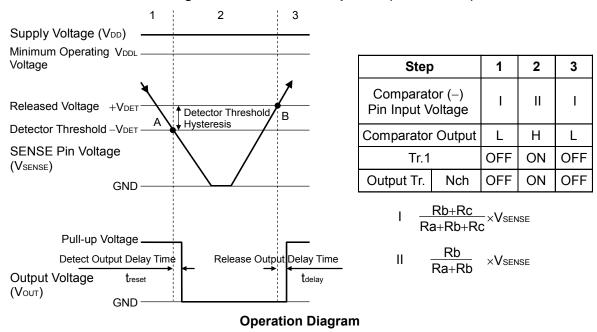
$$t_{delay}(s) = 4.545 \times 10^6 \times C_D(F)$$

OPERATION

Operation of R3118xxxxA



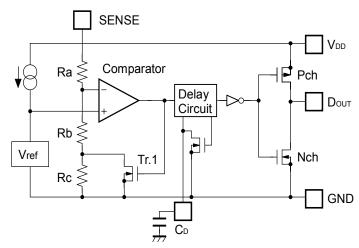
Block diagram with an external capacitor (R3118xxxxA)



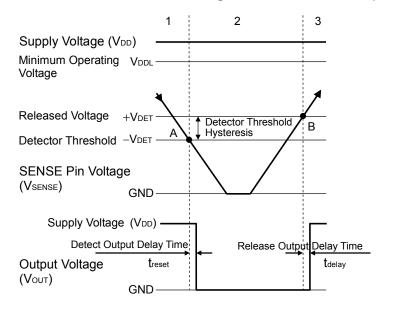
• Explanation of operation

- Step 1. The output voltage is equal to the pull-up voltage.
- Step 2. At Point "A", Vref ≤ V_{SENSE}×(Rb+Rc)/(Ra+Rb+Rc) is true, as a result, the output of comparator is reversed from "L" to "H", therefore the output voltage becomes the GND level. The voltage level of Point A means a detector threshold voltage (-V_{DET}). (When the supply voltage is lower than the minimum operating voltage, the operation of the output transistor becomes indefinite. The output voltage is equal to the GND level.)
- Step 3. At Point "B", V_{ref} ≤ V_{SENSE}×Rb/(Ra+Rb) is true, as a result, the output of comparator is reversed from "H" to "L", then the output voltage is equal to the pull-up voltage. The voltage level of Point B means a released voltage (+V_{DET}).
- *) The difference between a released voltage and a detector threshold voltage is a detector threshold hysteresis.

Operation of R3118xxxxC



Block diagram with an external capacitor (R3118xxxxC)



Step	1	2	3	
Comparat Pin Input V	_	=	I	
Comparator	L	Н	L	
Tr.1	OFF	ON	OFF	
Output Tr.	Pch	ON	OFF	ON
Output 11.	Nch	OFF	ON	OFF

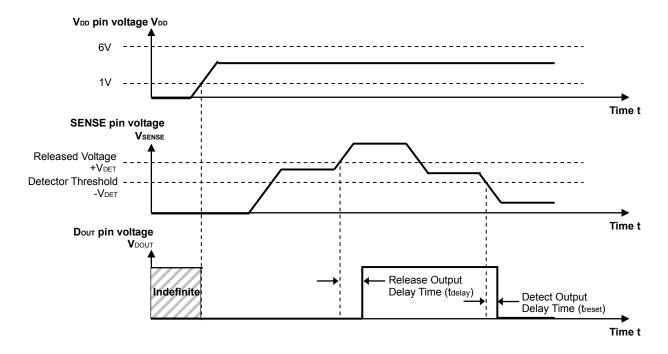
I
$$\frac{Rb}{Ra+Rb+Rc} \times V_{SENSE}$$
II $\frac{Rb}{Ra+Rb} \times V_{SENSE}$

Operation Diagram

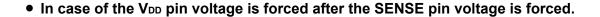
Explanation of operation

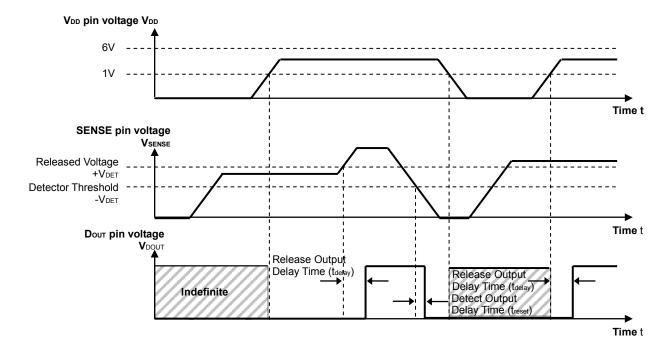
- Step 1. The output voltage is equal to the supply voltage (VDD).
- Step 2. At Point "A", V_{ref} ≥ V_{SENSE}×(Rb+Rc)/(Ra+Rb+Rc) is true, as a result, the output of comparator is reversed from "L" to "H", therefore the output voltage becomes the GND level. The voltage level of Point A means a detector threshold voltage (-V_{DET}). (When the supply voltage is lower than the minimum operating voltage, the operation of the output transistor becomes indefinite. The output voltage is equal to the GND level.)
- Step 3. At Point "B", V_{ref} ≤ V_{SENSE}×Rb/(Ra+Rb) is true, as a result, the output of comparator is reversed from "H" to "L", then the output voltage is equal to the supply voltage (V_{DD}). The voltage level of Point B means a released voltage (+V_{DET}).
- *) The difference between a released voltage and a detector threshold voltage is a detector threshold hysteresis.

• In case of the SENSE pin voltage is forced after the VDD pin voltage is forced.



If a power supply (in the range from 1V to 6V) is forced to V_{DD} pin and a voltage is forced to SENSE pin, when the SENSE pin voltage is less than released voltage + V_{DET} , D_{OUT} pin becomes "L". When the SENSE pin voltage is equal or more than the released voltage + V_{DET} , D_{OUT} pin becomes "H".



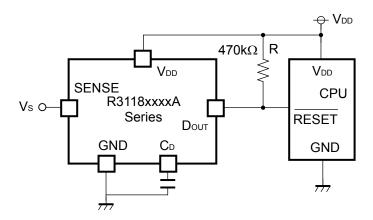


In the case of the SENSE pin voltage is less than released voltage $+V_{DET}$, when the V_{DD} pin voltage becomes to 1V or more, "L" output of D_{OUT} is determined. In case of the SENSE pin voltage is equal or more than the released voltage $+V_{DET}$, when the V_{DD} pin voltage becomes to 1V or more, "H" output of D_{OUT} is determined.

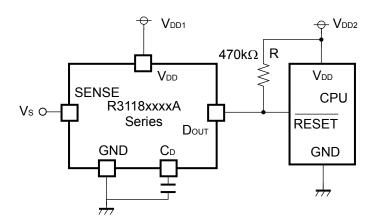
*) If the turn on speed of the supply voltage of the V_{DD} pin up to 1V is slower than the 1V/s, connect $0.001\mu F$ or more capacitor to C_D pin, otherwise, the output of D_{OUT} pin may indefinite.

TYPICAL APPLICATION

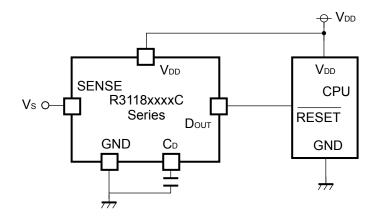
- R3118xxxxA CPU Reset Circuit (Nch Open Drain Output)
- (1) V_{DD} pin Voltage to R3118xxxxA is equal to V_{DD} pin Voltage to CPU



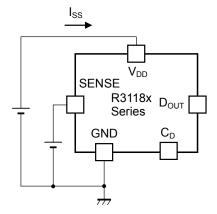
(2) VDD pin Voltage to R3118xxxxA is unequal to VDD pin Voltage to CPU



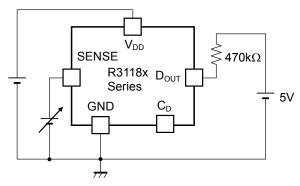
• R3118xxxxC CPU Reset Circuit (CMOS Output)



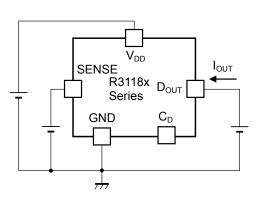
TEST CIRCUITS

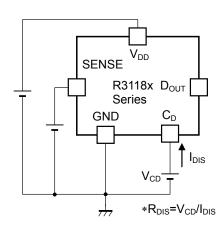


Supply Current Test Circuit

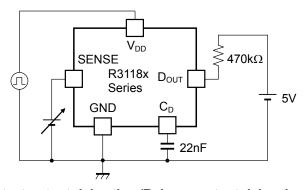


Detector Threshold Test Circuit(Pull-up circuit is not necessary for CMOS Output type.)





Nch/Pch Driver Output Current Test Circuit CD pin Discharge Transistor On resistance Test Circuit



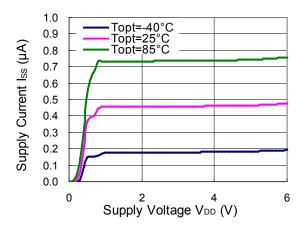
Detect output delay time/Release output delay time Test Circuit

(Pull-up circuit is not necessary for CMOS Output type.)

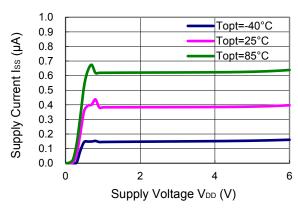
TYPICAL CHARACTERISTICS

1) Supply Current vs. Supply Voltage

R3118xxxxA/C (Vsense=0V)



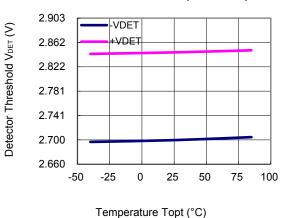
R3118xxxxA/C (Vsense=6V)



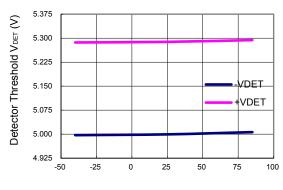
2) Detector Threshold vs. Temperature R3118x06xA/C (V_{DD}=5.3V)

Temperature Topt (°C)

R3118x27xA/C (VDD=5.3V)



R3118x50xA/C (VDD=5.3V)

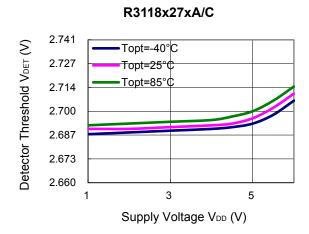


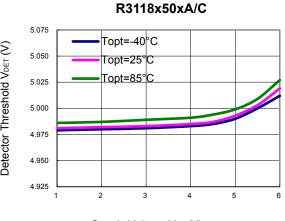
Temperature Topt (°C)

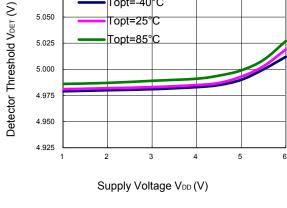
3) Detector Threshold vs. Supply Voltage

R3118x06xA/C 0.609 Topt=-40°C Detector Threshold VDET (V) 0.606 Topt=25°C Topt=85°C 0.603 0.600 0.597 0.594 0.591

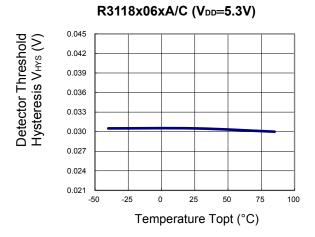
Supply Voltage V_{DD} (V)

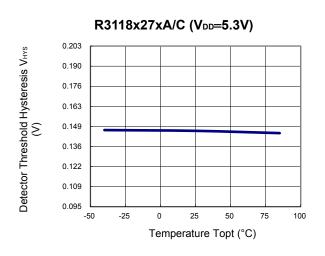




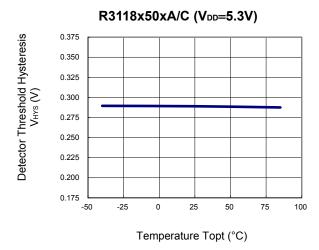


4) Hysteresis vs. Temperature

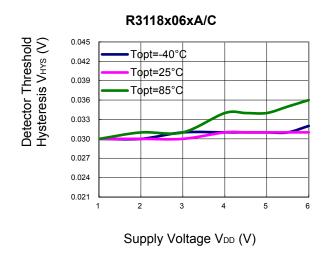


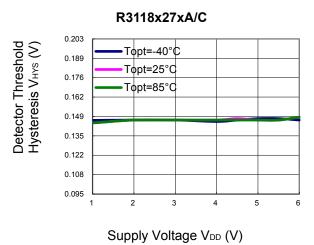


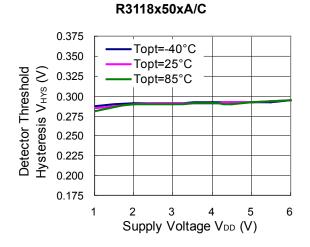
R3118x



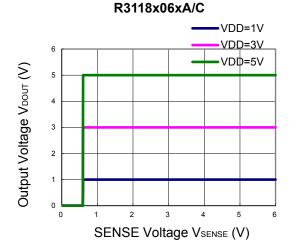
5) Hysteresis vs. Supply Voltage

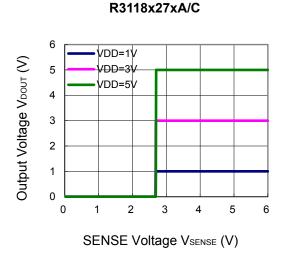




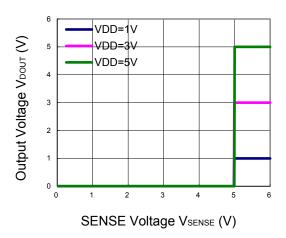


6) Output Voltage vs. SENSE Voltage (Dout pin is pulled up to Vpp pin via 470kΩ.)

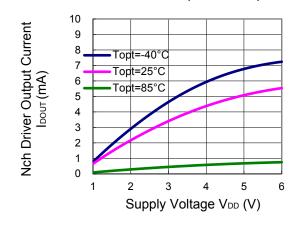




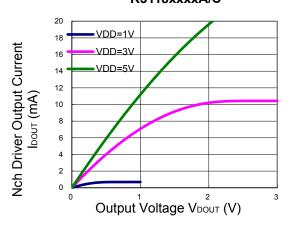
R3118x50xA/C



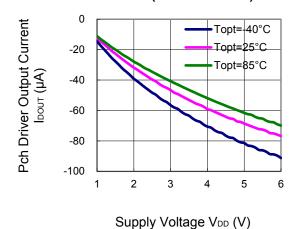
7) Nch Driver Output Current vs. Supply Voltage R3118xxxxA/C (VDOUT=0.4V)



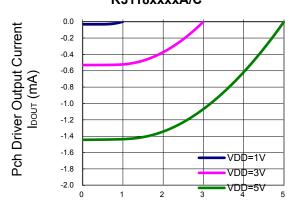
8) Nch Driver Output Current vs. Output Voltage R3118xxxxA/C



9) Pch Driver Output Current vs. Supply Voltage R3118xxxxA/C (VDOUT=VDD-0.1V)

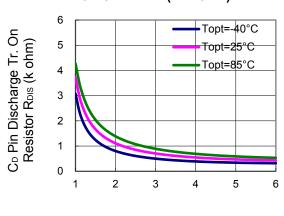


10) Pch Driver Output current vs. Output voltage R3118xxxxA/C



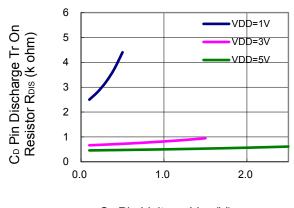
Output Voltage VDOUT (V)

11) C_D pin Discharge Tr. On Resistance vs. Supply Voltage R3118xxxxA/C (V_{CD}=0.4V)



Supply Voltage VDD (V)

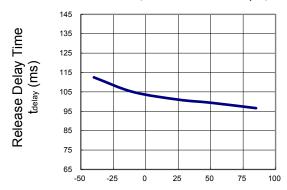
12) C_D pin Discharge Transistor On Resistance vs. C_D pin voltage R3118xxxxA/C



C_D Pin Voltage V_{CD} (V)

13) Release Output Delay Time vs. Temperature

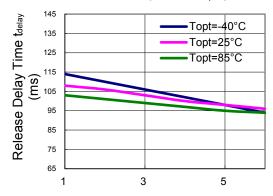
R3118xxxxA/C ($V_{DD}=4V$, $C_{D}=0.022\mu F$)



Temperature Topt (°C)

14) Release Output Delay Time vs. Supply Voltage

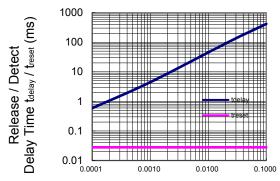
R3118xxxxA/C ($C_D=0.022\mu F$)



Supply Voltage VDD (V)

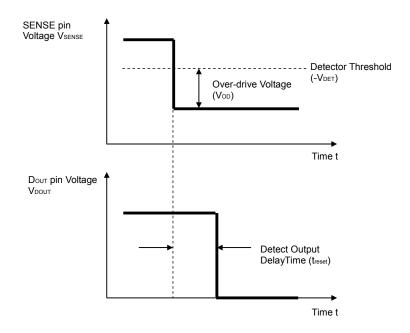
15) Detect Output Delay Time/Release Output Delay Time vs. C_D pin External Capacitance

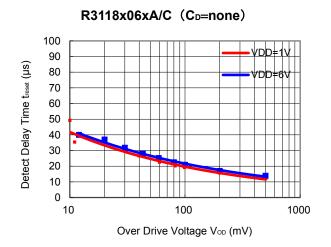
R3118xxxxA/C (VDD=4V)

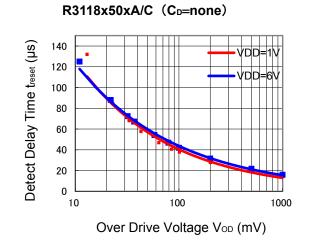


External Capacitance C_D (µF)

16) Detect Output Delay time vs. Over-drive Voltage

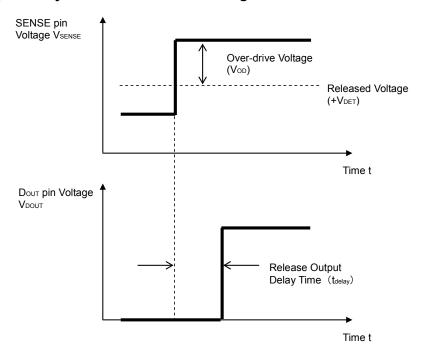




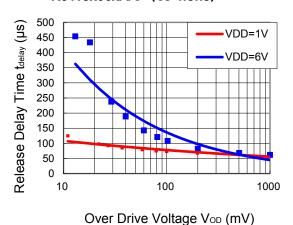


The pulse shorter than the detect output delay time cannot be detected, and "L" does not output from Dout pin.

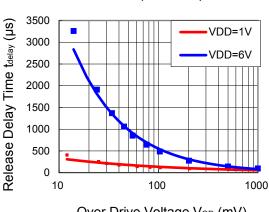
17) Release Output Delay time vs. Over-drive Voltage







R3118x50xA/C (C_D=none)



- Over Drive Voltage VoD (mV)
- · If the pulse is shorter than the output release delay time, the R3118 cannot be released and "H" does not output from Dout pin.
- · If the attachment capacitor for CD pin for setting a delay time is too small and the difference between the released voltage threshold and the actual released voltage is too small or the slope for rising voltage of the SENSE pin is too slow, the output delay time tolerance will be worse.
- Ex. Attachment capacitor=0.0001μF, Released voltage threshold=4.725V, Actual released voltage=4.75V In this case, the calculated delay time=0.4545ms, however, over-drive voltage is only 25mV. Therefore, the actual delay time will be approximately 2.4545ms. If the attachment capacitor=0.001μF and other conditions are same as above, the calculated delay time=4.545ms, and the actual delay time will be approximately 6.545ms. If the attachment capacitor=0.01µF and other conditions are same as above, the calculated delay time=45.45ms, and the actual delay time will be approximately 47.45ms.

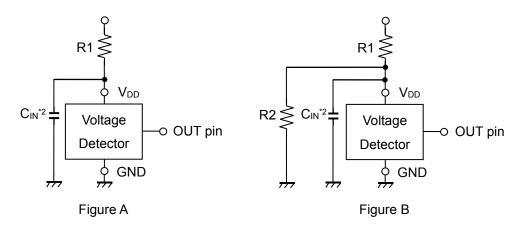
TECHNICAL NOTES

When connecting resistors to the device's input pin

When connecting a resistor (R1) to an input of this device, the input voltage decreases by [Device's Consumption Current] x [Resistance Value] only. And, the cross conduction current*1, which occurs when changing from the detecting state to the release state, is decreased the input voltage by [Cross Conduction Current] x [Resistance Value] only. And then, this device will enter the re-detecting state if the input voltage reduction is larger than the difference between the detector voltage and the released voltage.

When the input resistance value is large and the VDD is gone up at mildly in the vicinity of the released voltage, repeating the above operation may result in the occurrence of output.

As shown in Figure A/B, set R1 to become 100 k Ω or less as a guide, and connect C_{IN} of 0.1 μ F and more to between the input pin and GND. Besides, make evaluations including temperature properties under the actual usage condition, with using the evaluation board like this way. As a result, make sure that the cross conduction current has no problem.



^{*1} In the CMOS output type, a charging current for OUT pin is included.

^{*2} Note the bias dependence of capacitors.



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